



DEVICE TYPE:				SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006							
CUSTOMER:			DIE SIZE:								
WIRE TYPE/ SIZE:			NO. OF WIRES:								
THIRD ANGLE PROJECTION	REVISIONS					56 Lead 8mm x 8mm MLP Open-Pak Bonding Diagram					
	ECN NO.	DATE	DESCRIPTION	APPROVED							
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING		10504	10/27/05	PRODUCTION RELEASE	D.BENANDO						
DRAWN BY	W. GRIFFITTS	DATE	10/26/05	PACKAGE SIZE:	8.00mm x 8.00mm	SIZE	PART NO. MLP8X8-56-OP-01	REV	3		
APP BY	P. FLASKERUD	DATE	10/26/05	DIE PAD SIZE:	6.04mm x 6.04mm	SCALE		20X	CAD FILE	MLP8X8-56-OP-01-B-R3.DWG	SHEET